Bottom assembly

Placement plan, fitted-side orientation and native 3D reference

ASSEMBLY NOTES

01 View from outside the bottom. Bottom view is mirrored left to right.

02 Reference plan: 1:2 at A4 / 100%. The 170 mm board is drawn 85 mm wide.

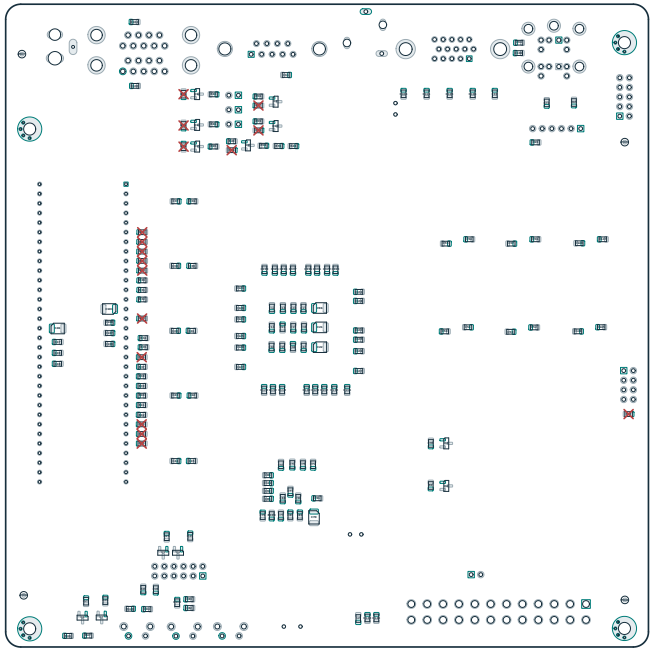
03 Teal marks pad 1 / A1. Check polarity and pin numbering against the footprint.

04 Red crosses mark saved DNP values. There are 18 options; native DNP flags are unset.

05 IC1: Spartan-3. IC2: ARM controller. IC3: MC68000. IC8-12: bus translation.

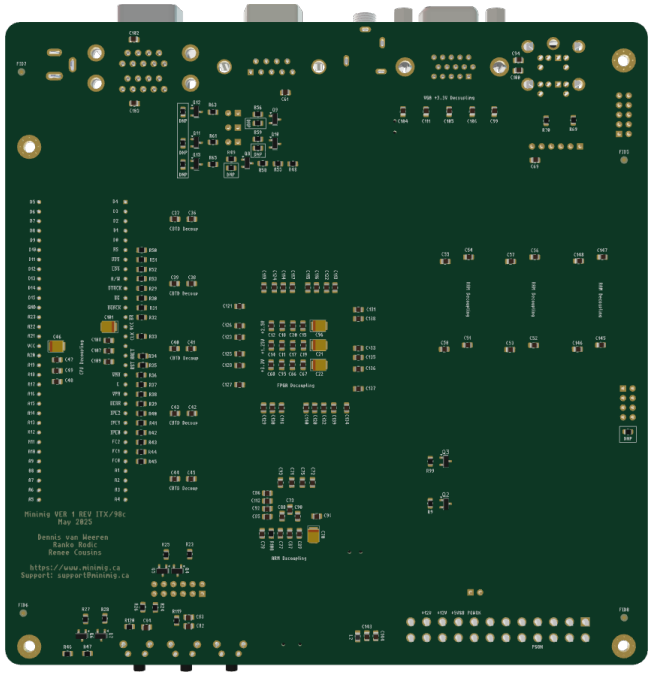
06 IC4-7 / IC13-14: six SRAMs, 6 MiB total. Shared 16-bit data and 19 address signals.

REFERENCE PLAN / 1:2



25 mm print check

3D ASSEMBLY VIEW



Ref	Drill	X	Y
H1	3.2	163.65	165.20
H2	3.2	163.65	33.02
H3	3.2	6.35	10.16
H4	3.2	6.35	165.10

Mounting holes H1-4 connect to Frame0. Outline: 170 × 170 mm, R4 corners; nominal thickness 1.6 mm. FID1-4 are on top; FID5-8 are on the bottom.

Hole coordinates use the top-view upper-left outline tangent: +X right, +Y down. This table is not mirrored.

Dennis, Ranko, Renee / Minimig.ca / Precision-Arrays

Revision 1.98itx | 2026-10-17 | PCB 2d3f20eb0dd8

Units: mm. Saved CAD governs. 3D views are illustrative.

A4 landscape. Print at 100% for the stated drawing scales.